

AM27MGC08

MEGA GREEN

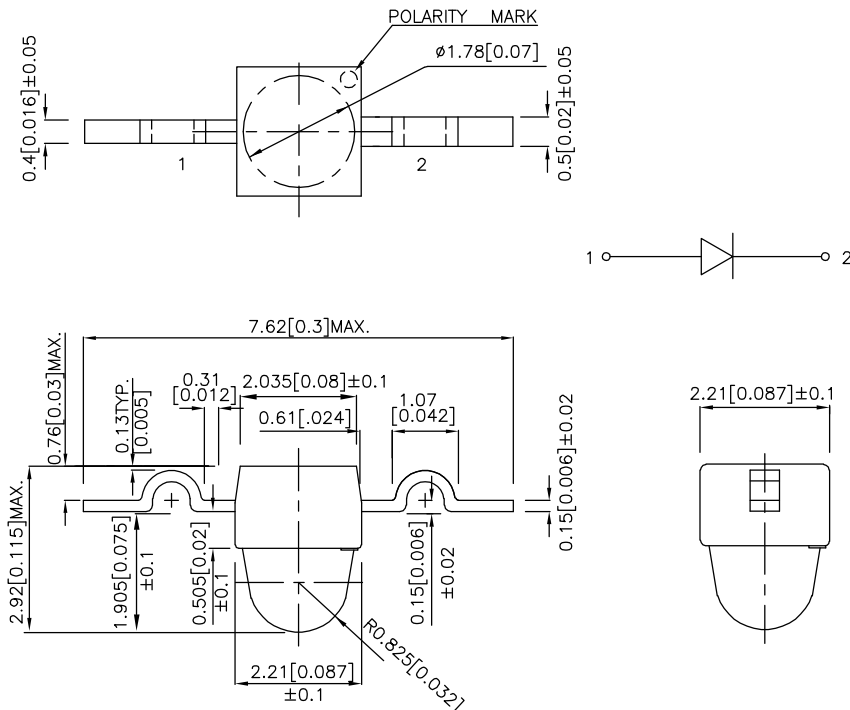
### Features

- SUBMINIATURE PACKAGE.
- WIDE VIEWING ANGLE.
- YOKE LEAD.
- LONG LIFE-SOLID STATE RELIABILITY.
- LOW PACKAGE PROFILE.
- PACKAGE : 1000PCS / REEL.
- RoHS COMPLIANT.

### Description

The Mega Green source color devices are made with DH InGaAlP on GaAs substrate Light Emitting Diode.

### Package Dimensions



#### Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is  $\pm 0.25(0.01)$  unless otherwise noted.
3. Lead spacing is measured where the leads emerge from the package.
4. Specifications are subject to change without notice.

## Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) @ 20mA		Viewing Angle
			Min.	Typ.	2 $\theta$ 1/2
AM27MGC08	MEGA GREEN (InGaAlP)	WATER CLEAR	280	600	20°

Note:

1.  $\theta$ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

## Electrical / Optical Characteristics at TA=25°C

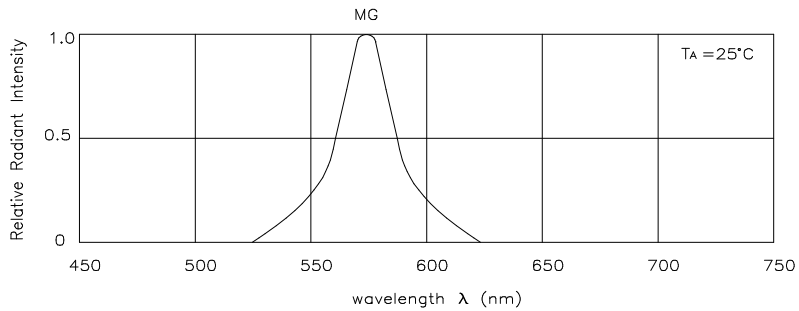
Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
$\lambda_{peak}$	Peak Wavelength	Mega Green	574		nm	IF=20mA
$\lambda_D$	Dominant Wavelength	Mega Green	568		nm	IF=20mA
$\Delta\lambda_{1/2}$	Spectral Line Half-width	Mega Green	26		nm	IF=20mA
C	Capacitance	Mega Green	20		pF	VF=0V;f=1MHz
VF	Forward Voltage	Mega Green	2.1	2.5	V	IF=20mA
IR	Reverse Current	Mega Green		10	uA	VR = 5V

## Absolute Maximum Ratings at TA=25°C

Parameter	Mega Green	Units
Power dissipation	105	mW
DC Forward Current	30	mA
Peak Forward Current [1]	150	mA
Reverse Voltage	5	V
Operating / Storage Temperature	-40°C To +85°C	

Note:

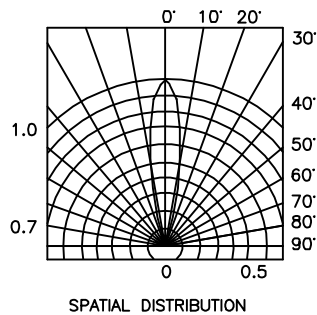
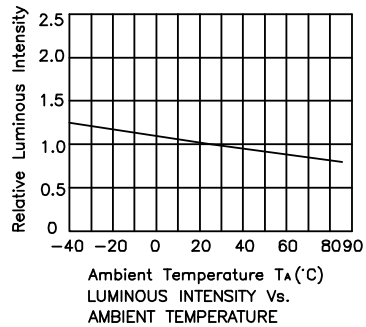
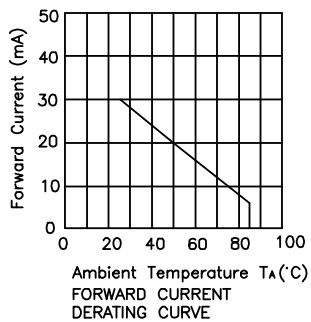
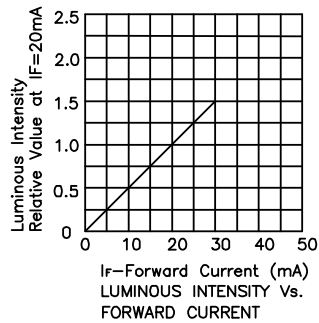
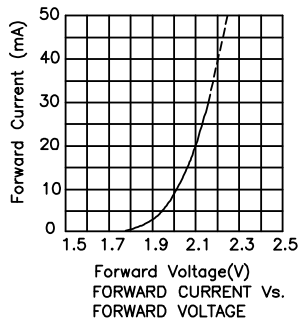
1. 1/10 Duty Cycle, 0.1ms Pulse Width.



RELATIVE INTENSITY Vs. WAVELENGTH

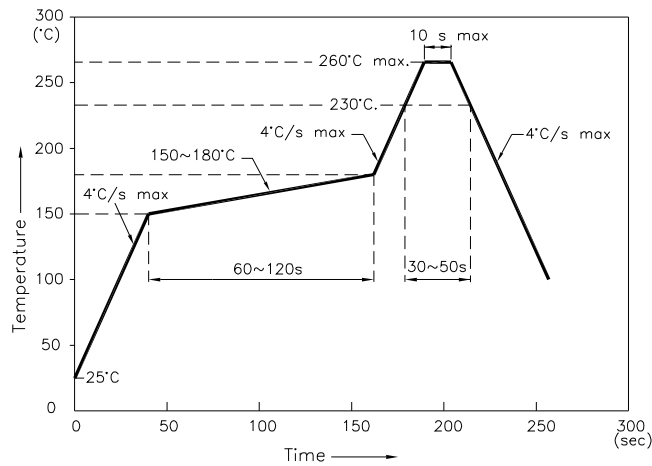
## Mega Green

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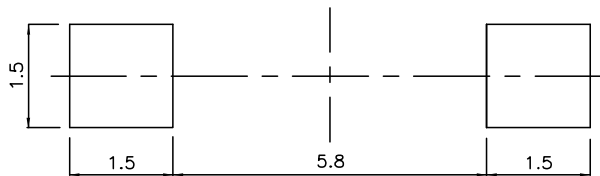
Reflow Soldering Profile For Lead-free SMT Process.



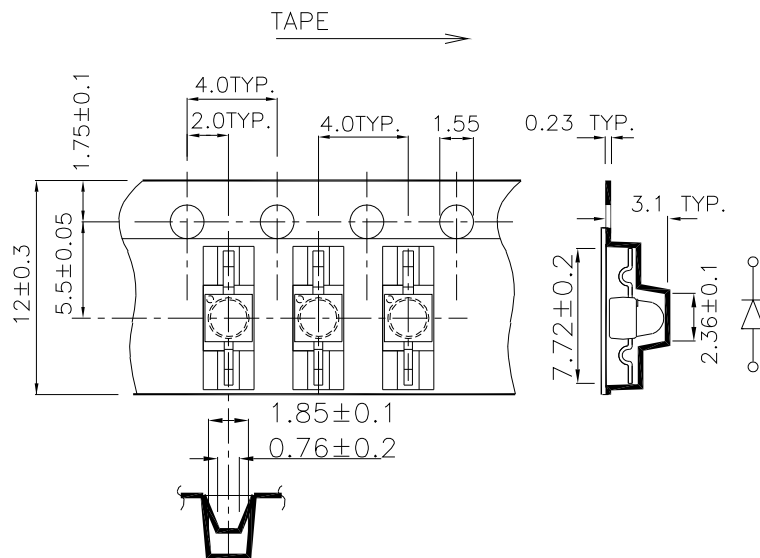
**NOTES:**

1. We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

### Recommended Soldering Pattern (Units : mm)

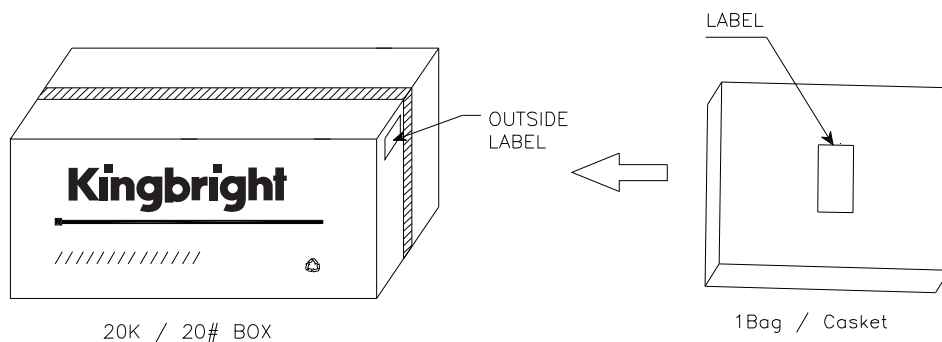
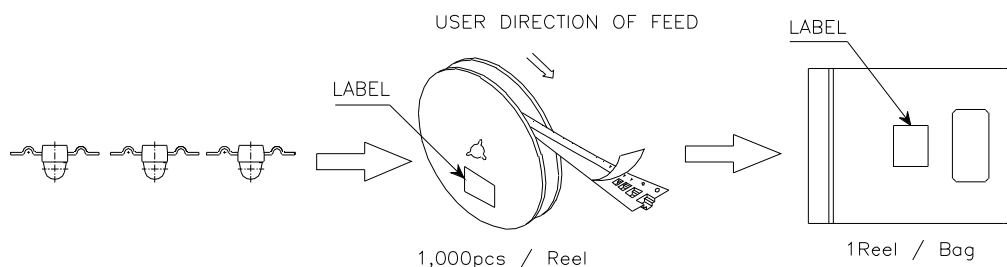



### Tape Specifications (Units : mm)



## PACKING & LABEL SPECIFICATIONS

**AM27MGC08**



<b>Kingbright</b>	
P/N0: AM27XXX08	
QTY: 1,000 pcs	Q.C. <span style="border: 1px solid black; border-radius: 50%; padding: 2px;">Q C xx xx xxxx PASSED</span>
S/N: XXXX	Date
CODE: XXX	
LOT NO:	
 <small>xxxxxxxxxxxxxxxxxxxxxxxxxxxxxxxx</small>	
RoHS Compliant	

**Remarks:**

If special sorting is required (e.g. binning based on forward voltage, luminous intensity, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm
2. Luminous Intensity: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.